

N-CHANNEL MOSFET

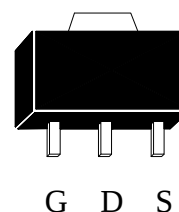
Features:

- Low on-resistance
- High speed switching
- Low-voltage drive
- Easily designed drive circuits
- Pb-free lead plating package

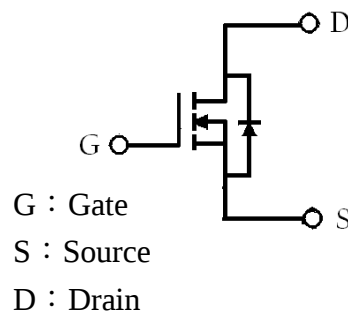
Description :

The KWN2328M3 is a N-channel enhancement-mode MOSFET.

SOT-89



BV_{DSS}	100V
I_D@V_{GS}=10V, T_A=25°C	3A
R_{DS(on)}@V_{GS}=10V, I_D=3A	130mΩ (typ)
R_{DS(on)}@V_{GS}=4.5V, I_D=3A	136mΩ (typ)



Ordering Information

Device	Package	Shipping
KWN2328M3	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / tape & reel

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DSS}	100	V
Gate-Source Voltage	V _{GSS}	±20	
Continuous Drain Current @V _{GS} =10V, T _A =25°C	I _D	3	A
Continuous Drain Current @V _{GS} =10V, T _A =100°C		1.9	
Pulsed Drain Current	I _{DM}	12 *1	
Total Power Dissipation	P _D	2.1 *2	W
Operating Junction and Storage Temperature Range	T _j ; T _{stg}	-55~+150	°C

Note : *1. Pulse Width ≤ 300μs, Duty cycle ≤ 2%

*2. When the device is surface mounted on 1 in² copper pad of FR-4 board with 2 oz. copper.

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient	R _{th,ja}	60	°C/W

Note : Surface mounted on 1 in² copper pad of FR-4 board.

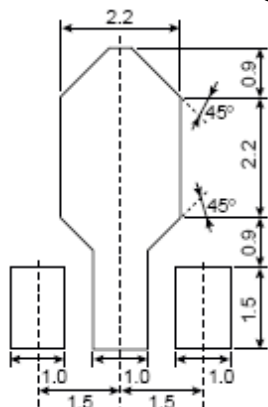
Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS} *	100	-	-	V	V _{GS} =0V, I _D =10μA
V _{GS(th)}	1	1.8	2.5		V _{DS} =V _{GS} , I _D =250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	1	μA	V _{DS} =100V, V _{GS} =0V
R _{DS(ON)} *	-	130	150	m	I _D =3A, V _{GS} =10V
	-	136	160		I _D =3A, V _{GS} =4.5V
G _{FS}	-	5	-	S	V _{DS} =10V, I _D =3A
Dynamic					
C _{iSS}	-	1188	-	pF	V _{DS} =25V, V _{GS} =0V, f=1MHz
C _{oSS}	-	30	-		
C _{rSS}	-	17	-		
td(ON)	-	7	-	ns	V _{DS} =50V, I _D =3A, V _{GS} =10V, R _{GEN} =6Ω
tr	-	3.2	-		
td(OFF)	-	29	-		
tf	-	5	-		
Qg	-	18.4	-	nC	V _{DS} =50V, I _D =3A, V _{GS} =10V
Qgs	-	4	-		
Qgd	-	7.5	-		
Source-Drain Diode					
*I _S	-	-	3	A	
*I _{SM}	-	-	12		

*V _{SD}	-	-	1.2	V	V _{GS} =0V, I _S =3A
*trr	-	45	-	ns	I _F =3A, dI _F /dt=100A/μs
*Q _{rr}	-	70	-	nC	

*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

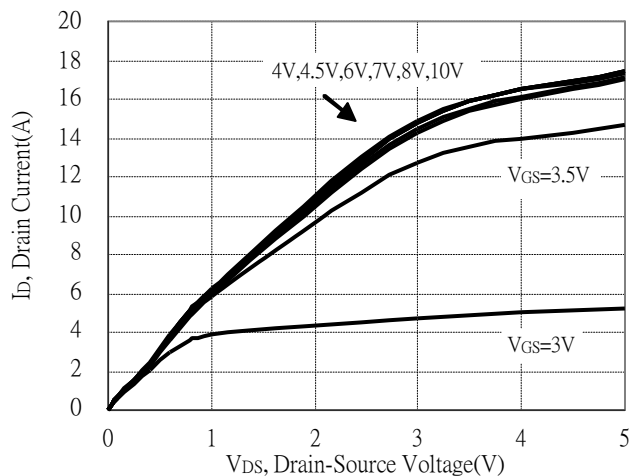
Recommended soldering footprint



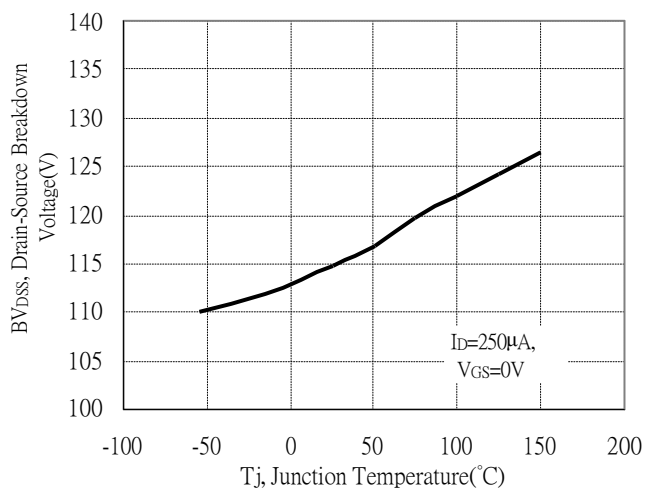
unit : mm

Typical Characteristics

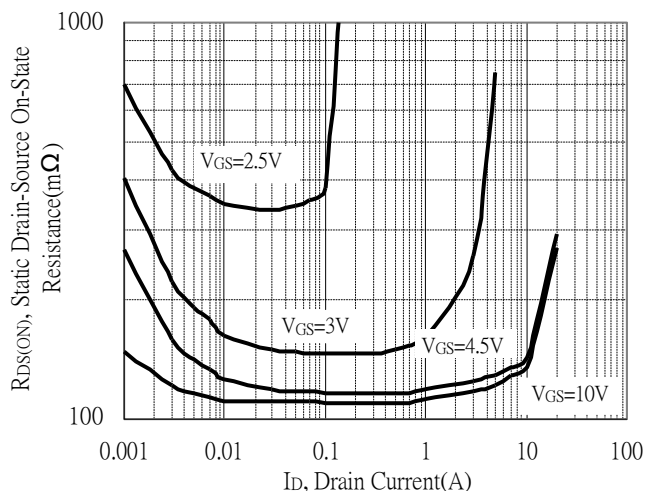
Typical Output Characteristics



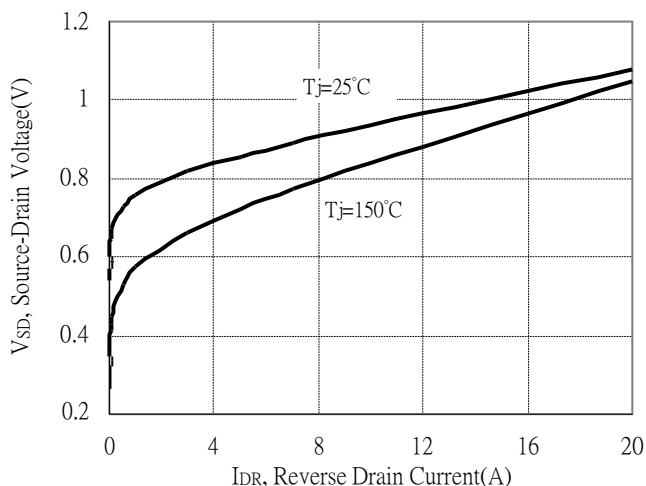
Breakdown Voltage vs Ambient Temperature



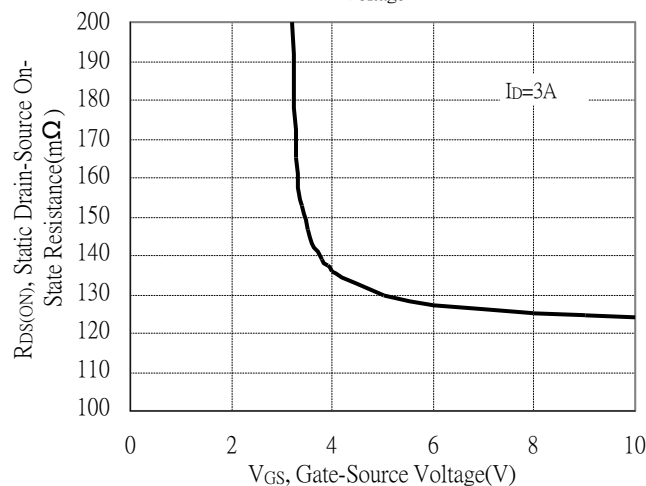
Static Drain-Source On-State resistance vs Drain Current



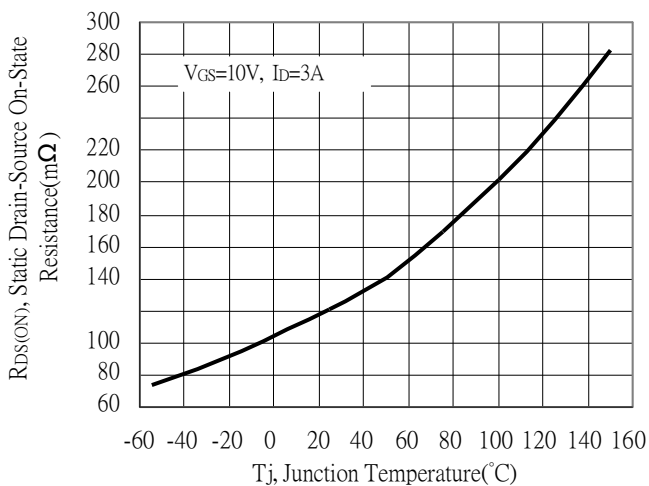
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

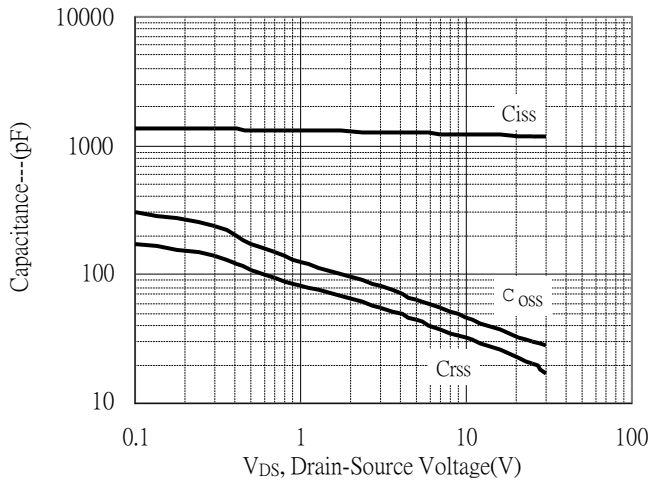


Drain-Source On-State Resistance vs Junction Temperature

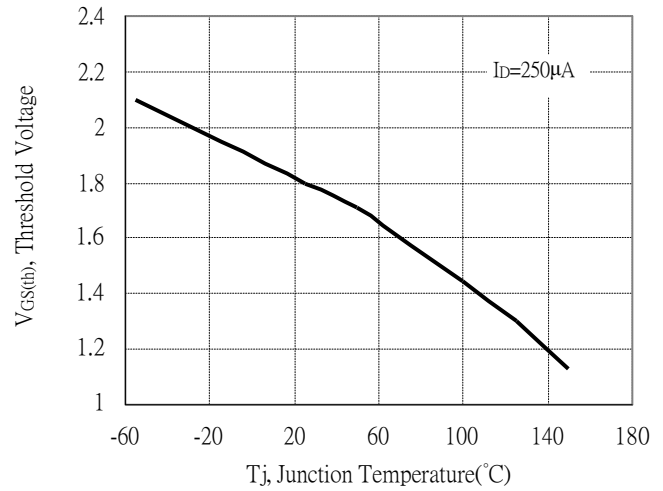


Typical Characteristics(Cont.)

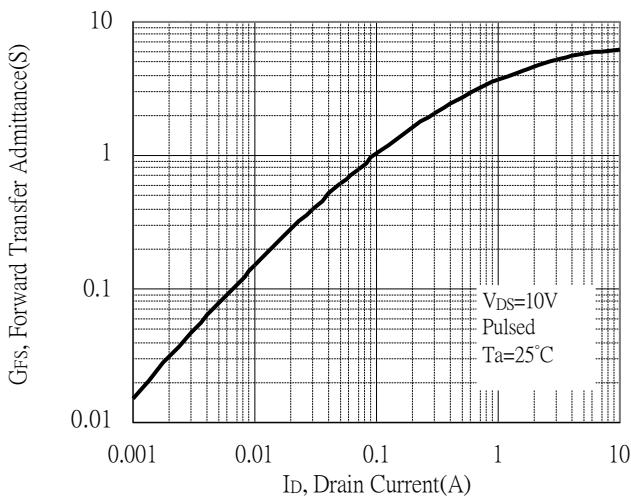
Capacitance vs Drain-to-Source Voltage



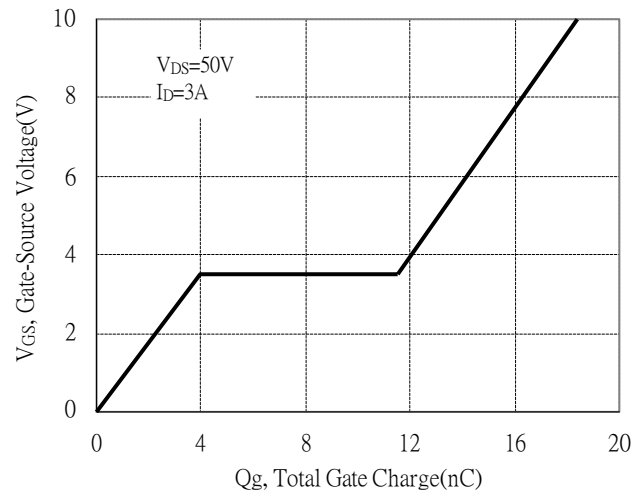
Threshold Voltage vs Junction Temperature



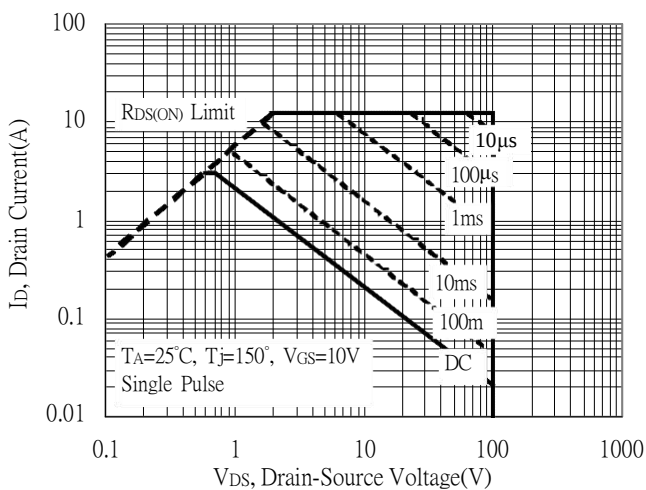
Forward Transfer Admittance vs Drain Current



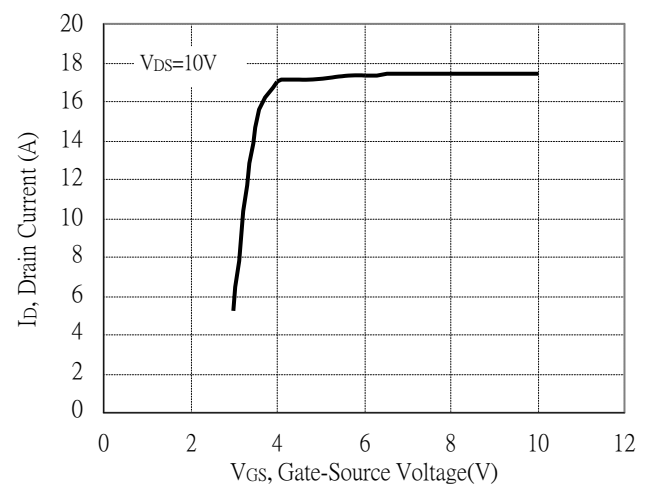
Gate Charge Characteristics



Maximum Safe Operating Area

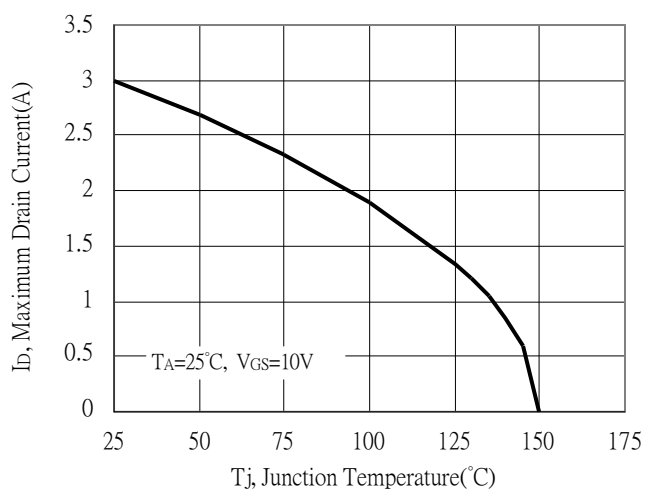


Typical Transfer Characteristics

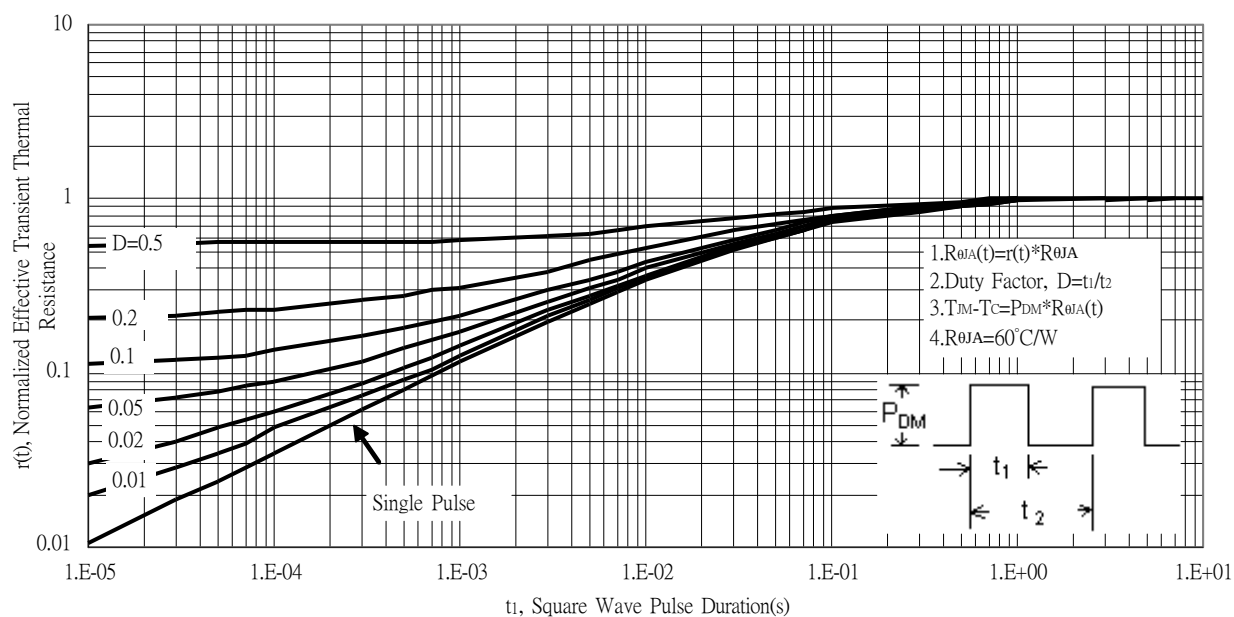


Typical Characteristics(Cont.)

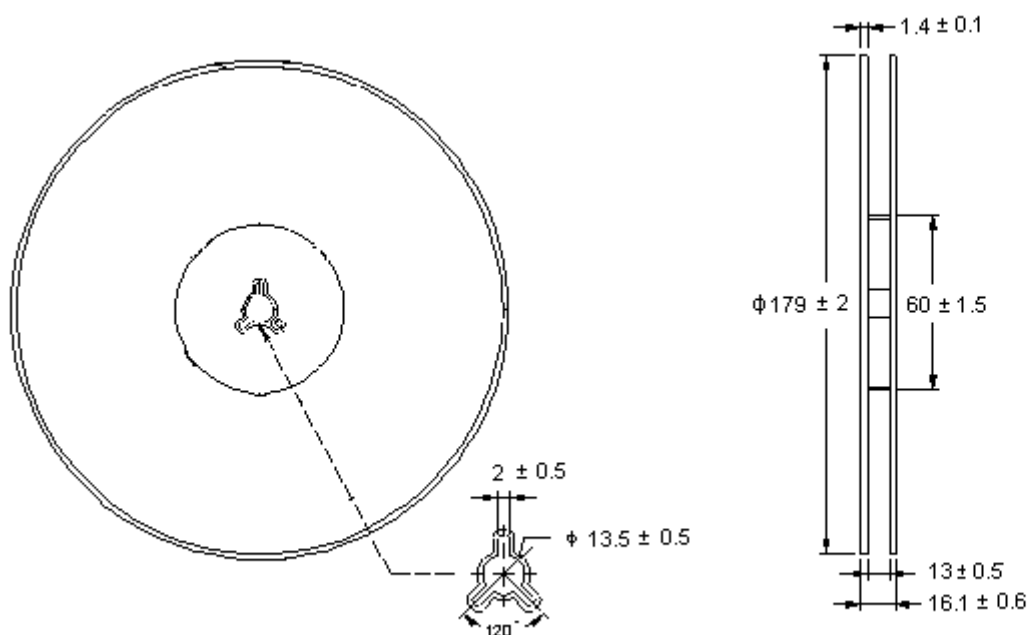
Maximum Drain Current vs Junction Temperature



Transient Thermal Response Curves

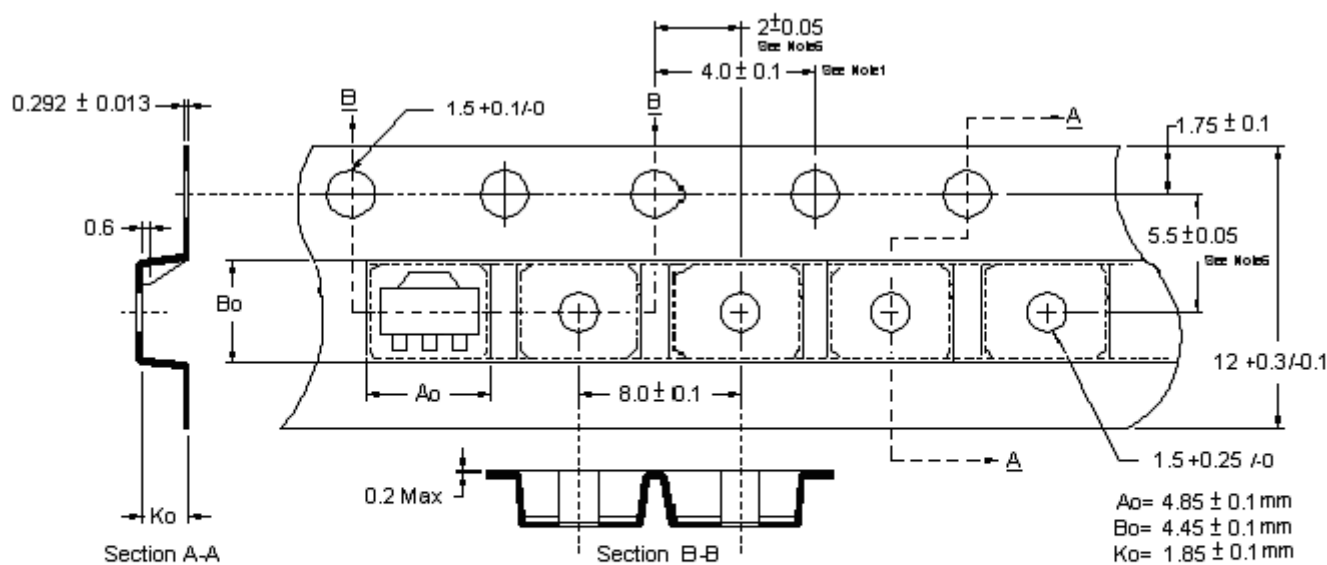


Reel Dimension



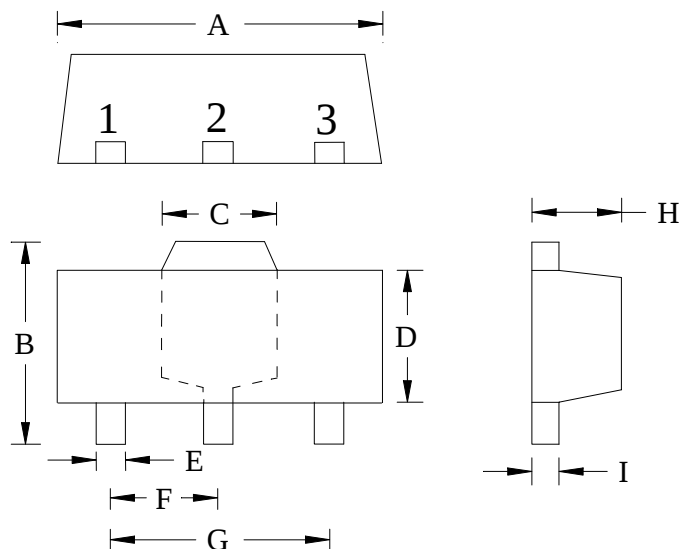
Unit: millimeter

Carrier Tape Dimension

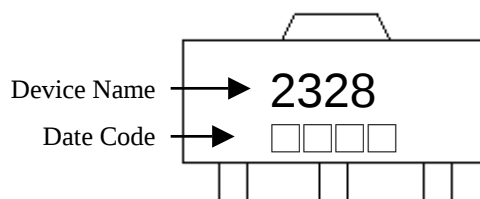


Unit : millimeter

SOT-89 Dimension



Marking:



Style: Pin 1. Gate 2. Drain 3. Source

3-Lead SOT-89 Plastic
 Surface Mounted Package
 Package Code: M3

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591	TYP	1.50	TYP
B	0.1551	0.1673	3.94	4.25	G	0.1181	TYP	3.00	TYP
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					